

H<sup>1</sup>  
cont'd.  
a first insulation film which is filling spaces between said plurality of conductor patterns where the contact hole is not formed and not extending over the etching stopper film, the first insulation film being in contact with side walls of the conductor patterns; and

a sidewall insulation film formed on an inner wall of the contact hole so that the side walls of the conductor pattern and the etching stopper film are covered.

36. (Thrice Amended) A semiconductor device comprising:  
a base substrate;  
a first conducting film formed over the base substrate and including two conductor patterns adjacent to each other;  
an etching stopper film covering each upper surface of the two conductor patterns;  
a first insulation film formed over the etching stopper film and the base substrate, the first insulation film being in contact with the side walls of the two conductor patterns;  
a contact hole, located between the two conductor patterns, reaching the base substrate through the first insulation film, wherein an end of the contact hole is positioned on the etching stopper film; and  
a sidewall insulation film formed on an inner wall of the first insulation film, each side wall of the two conductor patterns, and each side wall of the etching stopper film in the contact hole, in which

H<sup>2</sup>  
the end of the contact hole is defined by four sides including a first pair of sides which are opposed to each other and a second pair of sides which are opposed to each other,

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the first pair of sides is defined by the conductor patterns,

the second pair of sides is defined by the first insulation film.

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